

L Number	Hits	Search Text	DB	Time stamp
1	5284	324/72.5,158.1,601,130,202,765.ccls.	USPAT	2003/10/17 10:51
2	159	361/771.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/17 10:51
3	1612	174/261.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/17 10:51
4	332	calibrat\$4 near5 test\$4 near5 (wafer or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/17 10:54
5	34	324/72.5,158.1,601,130,202,765.ccls. and (calibrat\$4 near5 test\$4 near5 (wafer or substrate))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/17 10:53
6	0	361/771.ccls. and (calibrat\$4 near5 test\$4 near5 (wafer or substrate))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/17 10:53
7	0	174/261.ccls. and (calibrat\$4 near5 test\$4 near5 (wafer or substrate))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/17 10:53
8	2784	calibrat\$4 near5 (wafer or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/17 10:54
9	69	324/72.5,158.1,601,130,202,765.ccls. and (calibrat\$4 near5 (wafer or substrate))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/17 10:54
10	0	361/771.ccls. and (calibrat\$4 near5 (wafer or substrate))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/17 10:54
11	1	174/261.ccls. and (calibrat\$4 near5 (wafer or substrate))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/17 10:57
12	0	U5-6,476,630 U5-5,485,080 U5-6.326,801 U5-6,239,5906,420,892	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/17 10:57
13	0	U5-6,476,630 U5-5,485,080 U5-6.326,801 U5-6,239,590	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/17 10:57
14	10	(("6,420,892") or ("6,476,630") or ("5,485,080") or ("6,326,801") or ("6,239,590")).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/17 10:58
15	4	("5053700" "5389556" "5399505" "6037794").PN.	USPAT	2003/10/17 10:59

16	15	("4918374" "5004340" "5060371" "5483741" "5508629" "5599464" "5640101" "5656943" "5686317" "5869974" "5894161" "5915755" "6048750" "6060891" "6072321") .PN.	USPAT	2003/10/17 10:59
17	34	("4918374" "5004340" "5060371" "5150041" "5483741" "5508629" "5539676" "5599464" "5633122" "5640101" "5642056" "5656943" "5678301" "5686317" "5861759" "5869974" "5894161" "5915755" "5952840" "6048750" "6060891" "6072321" "6078186" "6107109" "6130148" "6181144" "6211960" "6218848" "6239590" "6246250" "6261854" "6275052" "6294837" "6300786") .PN.	USPAT	2003/10/17 11:01
18	3	786667.URPN.	USPAT	2003/10/17 11:02
-	246	calibrat\$4 near5 test\$4 near5 (wafer or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/17 10:52
-	219837	contact and conductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/06 16:45
-	54	(calibrat\$4 near5 test\$4 near5 (wafer or substrate)) and (contact and conductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/06 16:46
-	10	(calibrat\$4 near5 test\$4 near5 (wafer or substrate)) and 324/72.5, 601,130,202.ccls.	USPAT	2002/11/06 17:21
-	2	"6300757"	USPAT	2002/11/06 17:21
-	7	("5734268" "5748506" "5866437" "5884236" "5910011" "5929628" "6032107") .PN.	USPAT	2002/11/06 17:36
-	1	6300757.URPN.	USPAT	2002/11/06 17:37
-	776	calibrat\$4 same (contact same pair)	USPAT	2002/11/06 18:14
-	162	(calibrat\$4 same (contact same pair)) and (wafer or substrate or semiconductor)	USPAT	2002/11/06 17:50
-	6540	calibrat\$4 same (wafer or substrate or semiconductor)	USPAT	2002/11/06 18:14
-	230	(calibrat\$4 same (wafer or substrate or semiconductor)) and (contact with pair)	USPAT	2002/11/06 18:17
-	56	(calibrat\$4 same (wafer or substrate or semiconductor)) and ((contact with pair) with (semiconductor or wafer or substrate))	USPAT	2002/11/06 18:28
-	71	(calibrat\$4 same (wafer or substrate or semiconductor)) and (((contact or pad) with pair) with (semiconductor or wafer or substrate))	USPAT	2002/11/06 18:28
-	3603	calibrat\$4 with probe	USPAT	2002/11/07 13:12
-	652	(calibrat\$4 with probe) with system	USPAT	2002/11/07 13:13
-	96	((calibrat\$4 with probe) with system) and wafer	USPAT	2002/11/07 13:13
-	16876	"96" and (refer\$6 near3 point)	USPAT	2002/11/07 13:52
-	27	((calibrat\$4 with probe) with system) and wafer) and (refer\$6 near3 point)	USPAT	2002/11/07 14:43
-	1744	calibrat\$4 near5 contact	USPAT	2002/11/07 14:52

-	264	(calibrat\$4 near5 contact) and (wafer or semiconductor)	USPAT	2002/11/07 14:52
-	106	((calibrat\$4 near5 contact) and (wafer or semiconductor)) and probe	USPAT	2002/11/07 14:53
-	8	"5162728"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/16 17:57
-	4	((("4746861") or ("4780086"))).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/16 17:57
-	2	("5866998").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/17 10:48
-	0	316/771.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/17 11:54
-	153	361/771.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/17 11:54
-	1521	174/261.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/17 11:59
-	292	calibrat\$4 near5 test\$4 near5 (wafer or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/17 11:56
-	0	contact with lenght with trace	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/17 11:56
-	267	contact with length with trace	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/17 11:57
-	17	contact with equal with length with trace	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/17 11:58
-	1	(contact with equal with length with trace) and 324/750-765,158.1.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/17 11:58
-	0	(contact with equal with length with trace) and 316/771.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/17 11:59
-	0	(contact with equal with length with trace) and 361/771.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/17 11:59

-	1	(contact with equal with length with trace) and 174/261.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/17 15:51
-	633	324/755.ccls.	USPÄT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/17 15:51